PCA9633

4-bit I²C-bus LED driver

Rev. 01 — 23 January 2006 Product data sheet

1. General description

The PCA9633 is an I²C-bus controlled 4-bit LED driver optimized for Red/Green/Blue/Amber (RGBA) color mixing applications. Each LED output has its own 8-bit resolution (256 steps) fixed frequency Individual PWM controller that operates at 97 kHz with a duty cycle that is adjustable from 0 % to 99.6 % to allow the LED to be set to a specific brightness value. A fifth 8-bit resolution (256 steps) Group PWM controller has both a fixed frequency of 190 Hz and an adjustable frequency between 24 Hz to once every 10.73 seconds with a duty cycle that is adjustable from 0 % to 99.6 % that is used to either dim or blink all LEDs with the same value.

Each LED output can be off, on (no PWM control), set at its Individual PWM controller value or at both Individual and Group PWM controller values. The LED output driver is programmed to be either open-drain with a 25 mA current sink capability at 5 V or totem-pole with a 25 mA sink, 10 mA source capability at 5 V. The PCA9633 operates with a supply voltage range of 2.3 V to 5.5 V and the outputs are 5.5 V tolerant. LEDs can be directly connected to the LED output (up to 25 mA, 5.5 V) or controlled with external drivers and a minimum amount of discrete components for larger current LEDs or higher voltage LED strings.

The active LOW Output Enable input pin ($\overline{OE}$) allows asynchronous control of the LED outputs and can be used to set all the outputs to a defined I²C-bus programmable logic state. The $\overline{OE}$ can also be used to externally PWM the outputs, which is useful when multiple devices need to be dimmed or blinked together using software control. This feature is available for the 16-pin version only.

Software programmable LED Group and three Sub Call I²C addresses allow all or defined groups of PCA9633 devices to respond to a common I²C address, allowing for example, all red LEDs to be turned on or off at the same time or marquee chasing effect, thus minimizing I²C-bus commands.

The PCA9633 is offered with 3 different I²C-bus address options: fixed I²C-bus address (8-pin version), 2 programmable I²C-bus addresses (10-pin version), and 7 programmable I²C-bus addresses (16-pin version). They are software identical except for the different number of address combinations.

The Software Reset (SWRST) Call allows the master to perform a reset of the PCA9633 through the I²C-bus, identical to the Power-On Reset (POR) that initializes the registers to their default state causing the outputs to be set HIGH (LED off). This allows an easy and quick way to reconfigure all device registers to the same condition.

PHILIPS

2. Features

- 4 LED drivers. Each output programmable at:
  - Off
  - On
  - Programmable LED brightness
  - Programmable group dimming/blinking mixed with individual LED brightness
- 1 MHz Fast mode compatible I²C-bus interface with 30 mA high drive capability on SDA output for driving high capacitive buses
- 256-step (8-bit) linear programmable brightness per LED output varying from fully off (default) to maximum brightness using a 97 kHz PWM signal
- 256-step group brightness control allows general dimming (using a 190 Hz PWM signal) from fully off to maximum brightness (default)
- 256-step group blinking with frequency programmable from 24 Hz to 10.73 s and duty cycle from 0 % to 99.6 %
- Four totem-pole outputs (sink 25 mA and source 10 mA at 5 V) with software programmable open-drain LED outputs selection (default at totem-pole). No input function.
- Output state change programmable on the Acknowledge or the STOP Command to update outputs byte-by-byte or all at the same time (default to ‘Change on STOP’).
- Active LOW Output Enable ($\overline{OE}$) input pin. LED outputs programmable to ‘1’, ‘0’ or ‘high-impedance’ (default at power-up) when $\overline{OE}$ is HIGH, thus allowing hardware blinking and dimming of the LEDs (16-pin version only).
- 2 hardware address pins (10-pin version) and 7 hardware address pins (16-pin version) allow respectively up to 4 and 127 PCA9633 devices to be connected to the same I²C-bus. No hardware address pins in the 8-pin version.
- 4 software programmable I²C-bus addresses (one LED Group Call address and three LED Sub Call addresses) allow groups of devices to be addressed at the same time in any combination (for example, one register used for ‘All Call’ so that all the PCA9633s on the I²C-bus can be addressed at the same time and the second register used for three different addresses so that $\frac{1}{3}$ of all devices on the bus can be addressed at the same time in a group). Software enable and disable for I²C-bus address.
- Software Reset feature (SWRST Call) allows the device to be reset through the I²C-bus
- Up to 126 possible hardware adjustable individual I²C-bus addresses per device so that each device can be programmed individually.
- 25 MHz internal oscillator requires no external components
- Internal power-on reset
- Noise filter on SDA/SCL inputs
- Edge rate control on outputs
- No glitch on power-up
- Supports hot insertion
- Low standby current
- Operating power supply voltage range of 2.3 V to 5.5 V
- 5.5 V tolerant inputs
- –40 °C to +85 °C operation

- ESD protection exceeds 2000 V HBM per JESD22-A114, 200 V MM per JESD22-A115, and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- Packages offered: SO, TSSOP (MSOP), HVQFN, HVSON

3. Applications

- RGB or RGBA LED drivers
- Decorative LED lighting
- LED status information
- LED displays
- LCD backlights
- Keypad backlights for cellular phones or handheld devices

4. Ordering information

Table 1: Ordering information

Type number	Topside mark	Package		
		Name	Description	Version
PCA9633D16	PCA9633	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
PCA9633DP1	9633	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm	SOT505-1
PCA9633DP2	9633	TSSOP10	plastic thin shrink small outline package; 10 leads; body width 3 mm	SOT552-1
PCA9633PW	PCA9633	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
PCA9633BS	9633	HVQFN16	plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body $4 \times 4 \times 0.85$ mm	SOT629-1
PCA9633TK	9633	HVSON8	plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body $3 \times 3 \times 0.85$ mm	SOT908-1

5. Block diagram

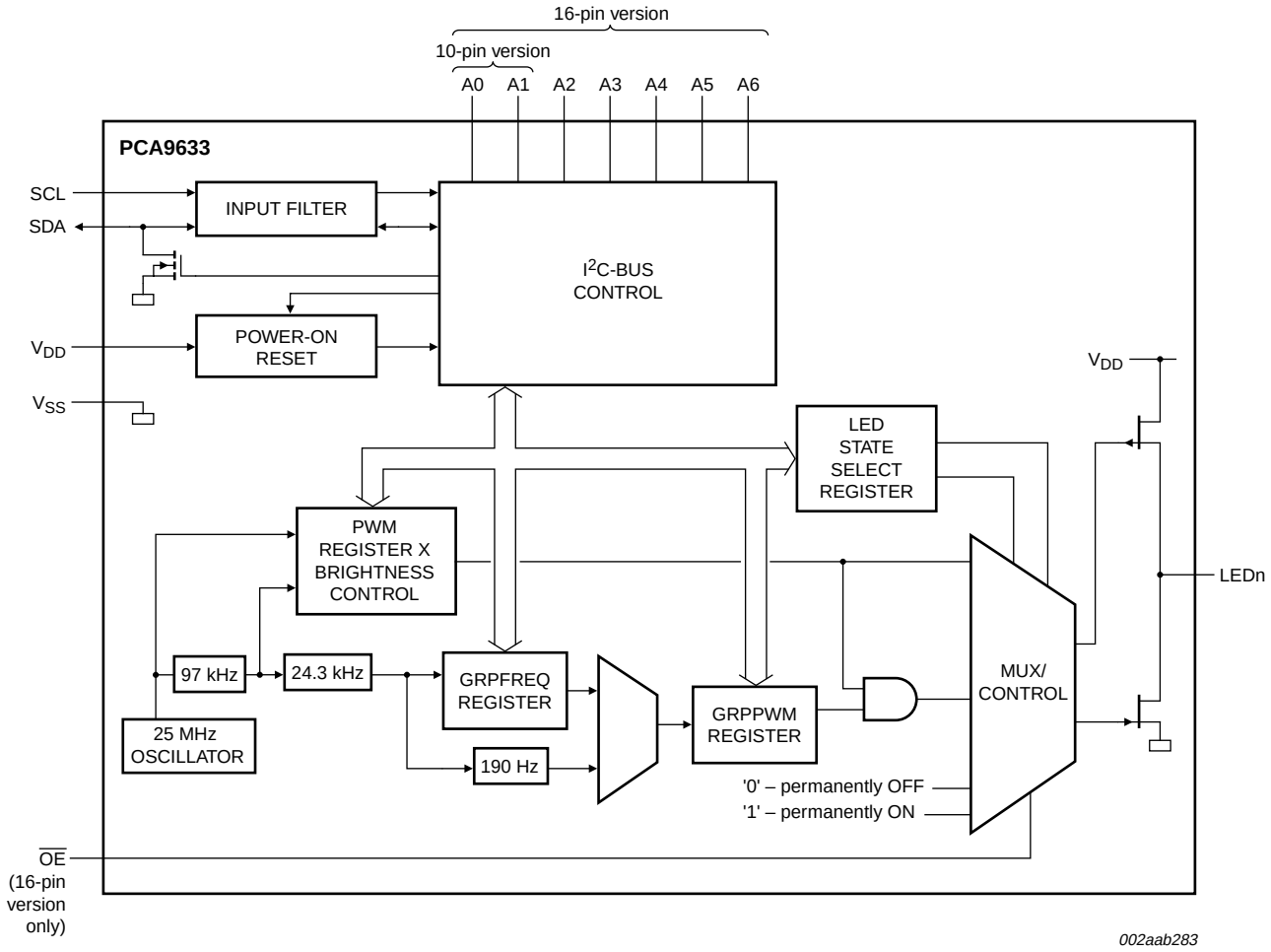


Fig 1. Block diagram of PCA9633

6. Pinning information

6.1 Pinning

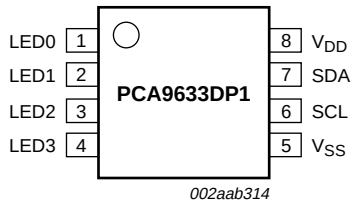


Fig 2. Pin configuration for TSSOP8

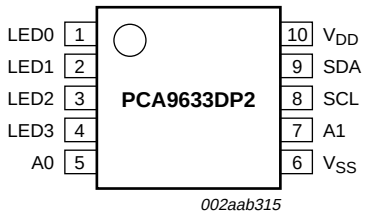


Fig 3. Pin configuration for TSSOP10

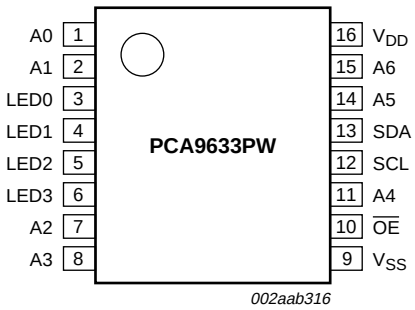


Fig 4. Pin configuration for TSSOP16

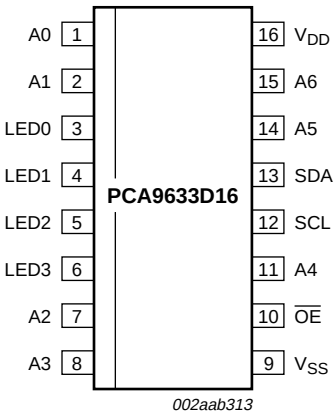
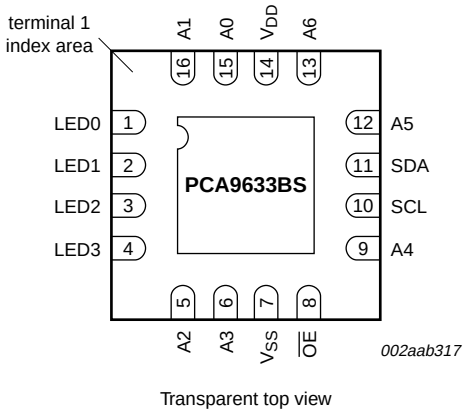
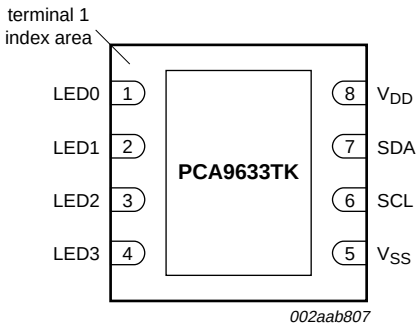


Fig 5. Pin configuration for SO16



Transparent top view

Fig 6. Pin configuration for HVQFN16



Transparent top view

Fig 7. Pin configuration for HVSON8

6.2 Pin description

Table 2: Pin description for TSSOP8 and HVSON8

Symbol	Pin	Type	Description
LED0	1	O	LED driver 0
LED1	2	O	LED driver 1
LED2	3	O	LED driver 2
LED3	4	O	LED driver 3
V_{SS}	5	power supply	supply ground
SCL	6	I	serial clock line
SDA	7	I/O	serial data line
V_{DD}	8	power supply	supply voltage

Table 3: Pin description for TSSOP10

Symbol	Pin	Type	Description
LED0	1	O	LED driver 0
LED1	2	O	LED driver 1
LED2	3	O	LED driver 2
LED3	4	O	LED driver 3
A0	5	I	address input 0
V_{SS}	6	power supply	supply ground
A1	7	I	address input 1
SCL	8	I	serial clock line
SDA	9	I/O	serial data line
V_{DD}	10	power supply	supply voltage

Table 4: Pin description for SO16 and TSSOP16

Symbol	Pin	Type	Description
A0	1	I	address input 0
A1	2	I	address input 1
LED0	3	O	LED driver 0
LED1	4	O	LED driver 1
LED2	5	O	LED driver 2
LED3	6	O	LED driver 3
A2	7	I	address input 2
A3	8	I	address input 3
V_{SS}	9	power supply	supply ground
$\overline{OE}$	10	I	active LOW Output Enable
A4	11	I	address input 4
SCL	12	I	serial clock line
SDA	13	I/O	serial data line
A5	14	I	address input 5
A6	15	I	address input 6
V_{DD}	16	power supply	supply voltage

Table 5: Pin description for HVQFN16

Symbol	Pin	Type	Description
LED0	1	O	LED driver 0
LED1	2	O	LED driver 1
LED2	3	O	LED driver 2
LED3	4	O	LED driver 3
A2	5	I	address input 2
A3	6	I	address input 3
V_{SS} [1]	7	power supply	supply ground
$\overline{OE}$	8	I	active LOW Output Enable
A4	9	I	address input 4
SCL	10	I	serial clock line
SDA	11	I/O	serial data line
A5	12	I	address input 5
A6	13	I	address input 6
V_{DD}	14	power supply	supply voltage
A0	15	I	address input 0
A1	16	I	address input 1

[1] HVQFN package die supply ground is connected to both the V_{SS} pin and the exposed center pad. The V_{SS} pin must be connected to supply ground for proper device operation. For enhanced thermal, electrical, and board-level performance, the exposed pad needs to be soldered to the board using a corresponding thermal pad on the board, and for proper heat conduction through the board thermal vias need to be incorporated in the PCB in the thermal pad region.

7. Functional description

Refer to Figure 1 “Block diagram of PCA9633”.

7.1 Device addresses

Following a START condition, the bus master must output the address of the slave it is accessing.

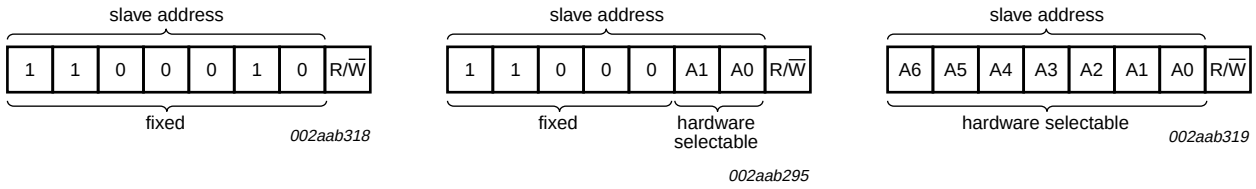
7.1.1 Regular I²C-bus slave address

The I²C-bus slave address of the PCA9633 is shown in Figure 8. To conserve power, no internal pull-up resistors are incorporated on the hardware selectable address pins and they must be pulled HIGH or LOW (10-pin and 16-pin versions).

CAUTION

For the 16-pin version, reserved I²C-bus addresses must be used with caution since they can interfere with:

- ‘reserved for future use’ I²C-bus addresses (0000011, 11111XX)
- slave devices that use the 10-bit addressing scheme (11110XX)
- slave devices that are designed to respond to the General Call address (0000000)
- High-speed mode (Hs-mode) master code (00001XX).



a. 8-pin version b. 10-pin version c. 16-pin version

Fig 8. Slave address

The last bit of the address byte defines the operation to be performed. When set to logic 1 a read is selected, while a logic 0 selects a write operation.

7.1.2 LED All Call I²C-bus address

- Default power-up value (ALLCALLADR register): 0xE0 or 1110000
- Programmable through I²C-bus (volatile programming)
- At power-up, LED All Call I²C-bus address is enabled. PCA9633 sends an ACK when 0xE0 (R/$\overline{W}$ = 0) or 0xE1 (R/$\overline{W}$ = 1) is sent by the master.

See Section 7.3.8 “LED All Call I²C-bus address, ALLCALLADR” for more detail.

CAUTION

The default LED All Call I²C-bus address (0xE0 or 1110000) must not be used as a regular I²C-bus slave address since this address is enabled at power-up. All the PCA9633s on the I²C-bus will acknowledge the address if sent by the I²C-bus master.

7.1.3 LED Sub Call I²C-bus addresses

- 3 different I²C-bus addresses can be used
- Default power-up values:
  - SUBADR1 register: 0xE2 or 1110001
  - SUBADR2 register: 0xE4 or 1110010
  - SUBADR2 register: 0xE8 or 1110100
- Programmable through I²C-bus (volatile programming)
- At power-up, Sub Call I²C-bus addresses are disabled. PCA9633 does not send an ACK when 0xE2 (R/$\overline{W}$ = 0) or 0xE3 (R/$\overline{W}$ = 1), 0xE4 (R/$\overline{W}$ = 0) or 0xE5 (R/$\overline{W}$ = 1), or 0xE8 (R/$\overline{W}$ = 0) or 0xE9 (R/$\overline{W}$ = 1) is sent by the master.

See Section 7.3.7 “I²C-bus sub-address 1 to 3, SUBADRx” for more detail.

CAUTION

The default LED Sub Call I²C-bus addresses may be used as regular I²C-bus slave addresses as long as they are disabled.

7.1.4 Software Reset I²C-bus address

The address shown in Figure 9 is used when a reset of the PCA9633 needs to be performed by the master. The Software Reset address (SWRST Call) must be used with R/$\overline{W}$ = 0. If R/$\overline{W}$ = 1, the PCA9633 does not acknowledge the SWRST. See Section 7.6 “Software Reset” for more detail.

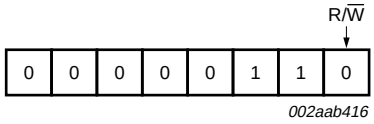


Fig 9. Software Reset address

CAUTION

The Software Reset I²C-bus address is a reserved address and cannot be used as a regular I²C-bus slave address (16-pin version) or as an LED All Call or LED Sub Call address.

7.2 Control register

Following the successful acknowledgement of the slave address, LED All Call address or LED Sub Call address, the bus master will send a byte to the PCA9633, which will be stored in the Control register.

The lowest 4 bits are used as a pointer to determine which register will be accessed (D[3:0]). The highest 3 bits are used as Auto-Increment flag and Auto-Increment options (AI[2:0]). Bit 4 is unused and must be programmed with zero (‘0’) for proper device operation.

reset state = 80h

Remark: The Control register does not apply to the Software Reset I²C-bus address.

Fig 10. Control register

When the Auto-Increment flag is set (AI2 = 1), the four low order bits of the Control register are automatically incremented after a read or write. This allows the user to program the registers sequentially. Four different types of Auto-Increment are possible, depending on AI1 and AI0 values.

Table 6: Auto-Increment options

AI2	AI1	AI0	Function
0	0	0	no Auto-Increment
1	0	0	Auto-Increment for all registers. D3, D2, D1, D0 roll over to ‘0000’ after the last register (1100) is accessed.
1	0	1	Auto-Increment for individual brightness registers only. D3, D2, D1, D0 roll over to ‘0010’ after the last register (0101) is accessed.
1	1	0	Auto-Increment for global control registers only. D3, D2, D1, D0 roll over to ‘0110’ after the last register (0111) is accessed.
1	1	1	Auto-Increment for individual and global control registers only. D3, D2, D1, D0 roll over to ‘0010’ after the last register (0111) is accessed.

Remark: Other combinations not shown in Table 6 (AI[2:0] = 001, 010, and 011) are reserved and must not be used for proper device operation.

AI[2:0] = 000 is used when the same register must be accessed several times during a single I²C-bus communication, for example, changes the brightness of a single LED. Data is overwritten each time the register is accessed during a write operation.

AI[2:0] = 100 is used when all the registers must be sequentially accessed, for example, power-up programming.

AI[2:0] = 101 is used when the four LED drivers must be individually programmed with different values during the same I²C-bus communication, for example, changing color setting to another color setting.

AI[2:0] = 110 is used when the LED drivers must be globally programmed with different settings during the same I²C-bus communication, for example, global brightness or blinking change.

AI[2:0] = 111 is used when individual and global changes must be performed during the same I²C-bus communication, for example, changing a color and global brightness at the same time.

Only the 4 least significant bits D[3:0] are affected by the AI[2:0] bits.

When the Control register is written, the register entry point determined by D[3:0] is the first register that will be addressed (read or write operation), and can be anywhere between 0000 and 1100 (as defined in Table 7). When AI[2] = 1, the Auto-Increment flag is set and the rollover value at which the point where the register increment stops and goes to the next one is determined by AI[2:0]. See Table 6 for rollover values. For example, if the Control register = 11101000 (0xE8), then the register addressing sequence will be (in hex):
08 → … → 0C → 00 → … → 07 → 02 → … → 07 → 02 → … → 07 → 02 → … as long as the master keeps sending or reading data.

7.3 Register definitions

Table 7: Register summary [1] [2]

Register number (hex)	D3	D2	D1	D0	Name	Type	Function
00	0	0	0	0	MODE1	read/write	Mode register 1
01	0	0	0	1	MODE2	read/write	Mode register 2
02	0	0	1	0	PWM0	read/write	brightness control LED0
03	0	0	1	1	PWM1	read/write	brightness control LED1
04	0	1	0	0	PWM2	read/write	brightness control LED2
05	0	1	0	1	PWM3	read/write	brightness control LED3
06	0	1	1	0	GRPPWM	read/write	group duty cycle control
07	0	1	1	1	GRPFREQ	read/write	group frequency
08	1	0	0	0	LEDOUT	read/write	LED output state
09	1	0	0	1	SUBADR1	read/write	I²C-bus sub-address 1
0A	1	0	1	0	SUBADR2	read/write	I²C-bus sub-address 2
0B	1	0	1	1	SUBADR3	read/write	I²C-bus sub-address 3
0C	1	1	0	0	ALLCALLADR	read/write	LED All Call I²C-bus address

[1] Only D[3:0] = 0000 to 1100 are allowed and will be acknowledged. D[3:0] = 1101, 1110, or 1111 are reserved and will not be acknowledged.

[2] When writing to the Control register, bit 4 must be programmed with '0' for proper device operation.

7.3.1 Mode register 1, MODE1

Table 8: MODE1 - Mode register 1(address 00h) bit description

*Legend: * default value*

Bit	Symbol	Access	Value	Description
7	AI2	read only	0	Register Auto-Increment disabled
			1*	Register Auto-Increment enabled
6	AI1	read only	0*	Auto-Increment bit 1 = 0
			1	Auto-Increment bit 1 = 1
5	AI0	read only	0*	Auto-Increment bit 0 = 0
			1	Auto-Increment bit 0 = 1
4	SLEEP	R/W	0	Normal mode. [1]
			1*	Low power mode. Oscillator off. [2]
3	SUB1	R/W	0*	PCA9633 does not respond to I²C-bus sub-address 1.
			1	PCA9633 responds to I²C-bus sub-address 1.
2	SUB2	R/W	0*	PCA9633 does not respond to I²C-bus sub-address 2.
			1	PCA9633 responds to I²C-bus sub-address 2.
1	SUB3	R/W	0*	PCA9633 does not respond to I²C-bus sub-address 3.
			1	PCA9633 responds to I²C-bus sub-address 3.
0	ALLCALL	R/W	0	PCA9633 does not respond to LED All Call I²C-bus address.
			1*	PCA9633 responds to LED All Call I²C-bus address.

[1] It takes 500 µs max. for the oscillator to be up and running once SLEEP bit has been set to '1'. Timings on LEDn outputs are not guaranteed if PWMx, GRPPWM or GRPFREQ registers are accessed within the 500 µs window.

[2] No blinking or dimming is possible when the oscillator is off.

7.3.2 Mode register 2, MODE2

Table 9: MODE2 - Mode register 2 (address 01h) bit description

*Legend: * default value*

Bit	Symbol	Access	Value	Description
7	-	read only	0*	reserved
6	-	read only	0*	reserved
5	DMBLNK	R/W	0*	Group control = dimming
			1	Group control = blinking
4	INVRT [1]	R/W	0*	Output logic state not inverted. Value to use when no external driver used. Applicable when $\overline{OE}$ = 0 for PCA9633 16-pin version.
			1	Output logic state inverted. Value to use when external driver used. Applicable when $\overline{OE}$ = 0 for PCA9633 16-pin version.
3	OCH	R/W	0*	Outputs change on STOP command. [2]
			1	Outputs change on ACK.
2	OUTDRV [1]	R/W	0	The 4 LED outputs are configured with an open-drain structure.
			1*	The 4 LED outputs are configured with a totem-pole structure.
1 to 0	OUTNE[1:0] [3] [4]	R/W	00	When $\overline{OE}$ = 1 (output drivers not enabled), LEDn = 0.
			01*	When $\overline{OE}$ = 1 (output drivers not enabled): LEDn = 1 when OUTDRV = 1 LEDn = high-impedance when OUTDRV = 0 (same as OUTNE[1:0] = 10)
			10	When $\overline{OE}$ = 1 (output drivers not enabled), LEDn = high-impedance.
			11	reserved

[1] See Section 7.7 “Using the PCA9633 with and without external drivers” for more details.

[2] Change of the outputs at the STOP command allows synchronizing outputs of more than one PCA9633. Applicable to registers from 0x02 (PWM0) to 0x08 (LEDOUT) only.

[3] See Section 7.4 “Active LOW output enable input” for more details.

[4] OUTNE[1:0] is only for PCA9633 16-pin version.

7.3.3 PWM registers 0 to 3, PWMx—Individual brightness control registers

Table 10: PWM0 to PWM3 - PWM registers 0 to 3 (address 02h to 05h) bit description

*Legend: * default value*

Address	Register	Bit	Symbol	Access	Value	Description
02h	PWM0	7:0	IDC0[7:0]	R/W	00000000*	PWM0 Individual Duty Cycle
03h	PWM1	7:0	IDC1[7:0]	R/W	00000000*	PWM1 Individual Duty Cycle
04h	PWM2	7:0	IDC2[7:0]	R/W	00000000*	PWM2 Individual Duty Cycle
05h	PWM3	7:0	IDC3[7:0]	R/W	00000000*	PWM3 Individual Duty Cycle

A 97 kHz fixed frequency signal is used for each output. Duty cycle is controlled through 256 linear steps from 0x00 (0 % duty cycle = LED output off) to 0xFF (99.6 % duty cycle = LED output at maximum brightness). Applicable to LED outputs programmed with LDRx = 10 or 11 (LEDOUT register).

$$\text{duty cycle} = \frac{IDC[7:0]}{256}$$

7.3.4 Group duty cycle control, GRPPWM

Table 11: GRPPWM - Group brightness control register (address 06h) bit description
*Legend: * default value*

Address	Register	Bit	Symbol	Access	Value	Description
06h	GRPPWM	7:0	GDC[7:0]	R/W	11111111	GRPPWM register

When DMBLNK bit (MODE2 register) is programmed with '0', a 190 Hz fixed frequency signal is superimposed with the 97 kHz individual brightness control signal. GRPPWM is then used as a global brightness control allowing the LED outputs to be dimmed with the same value. The value in GRPFREQ is then a 'Don't care'.

General brightness for the 4 outputs is controlled through 256 linear steps from 0x00 (0 % duty cycle = LED output off) to 0xFF (99.6 % duty cycle = maximum brightness). Applicable to LED outputs programmed with LDRx = 11 (LEDOUT register).

When DMBLNK bit is programmed with '1', GRPPWM and GRPFREQ registers define a global blinking pattern, where GRPFREQ contains the blinking period (from 24 Hz to 10.73 s) and GRPPWM the duty cycle (ON/OFF ratio in %).

$$\text{duty cycle} = \frac{\text{GDC[7:0]}}{256}$$

7.3.5 Group frequency, GRPFREQ

Table 12: GRPFREQ - Group Frequency register (address 07h) bit description
*Legend: * default value*

Address	Register	Bit	Symbol	Access	Value	Description
07h	GRPFREQ	7:0	GFRQ[7:0]	R/W	00000000*	GRPFREQ register

GRPFREQ is used to program the global blinking period when DMBLNK bit (MODE2 register) is equal to '1'. Value in this register is a 'Don't care' when DMBLNK = 0. Applicable to LED outputs programmed with LDRx = 11 (LEDOUT register).

Blinking period is controlled through 256 linear steps from 0x00 (41 ms, frequency 24 Hz) to 0xFF (10.73 s).

$$\text{global blinking period} = \frac{\text{GFRQ[7:0]} + 1}{24} \text{ (in seconds)}$$

7.3.6 LED driver output state, LEDOUT

Table 13: LEDOUT - LED driver output state register (address 08h) bit description
*Legend: * default value*

Address	Register	Bit	Symbol	Access	Value	Description
08h	LEDOUT	7:6	LDR3	R/W	00*	LED3 output state control
		5:4	LDR2	R/W	00*	LED2 output state control
		3:2	LDR1	R/W	00*	LED1 output state control
		1:0	LDR0	R/W	00*	LED0 output state control

LDRx = 00 — LED driver x is off (default power-up state).

LDRx = 01 — LED driver x is fully on (individual brightness and group dimming/blinking not controlled).

LDRx = 10 — LED driver x individual brightness can be controlled through its PWMx register.

LDRx = 11 — LED driver x individual brightness and group dimming/blinking can be controlled through its PWMx register and the GRPPWM registers.

7.3.7 I²C-bus sub-address 1 to 3, SUBADRx

Table 14: SUBADR1 to SUBADR3 - I²C-bus sub-address registers 0 to 3 (address 09h to 0Bh) bit description

*Legend: * default value*

Address	Register	Bit	Symbol	Access	Value	Description
09h	SUBADR1	7:1	A1[7:1]	R/W	1110001*	I²C-bus sub-address 1
		0	A1[0]	R only	0*	reserved
0Ah	SUBADR2	7:1	A2[7:1]	R/W	1110010*	I²C-bus sub-address 2
		0	A2[0]	R only	0*	reserved
0Bh	SUBADR3	7:1	A3[7:1]	R/W	1110100*	I²C-bus sub-address 3
		0	A3[0]	R only	0*	reserved

Sub-addresses are programmable through the I²C-bus. Default power-up values are 0xE2, 0xE4, 0xE8, and the device(s) will not acknowledge these addresses right after power-up (the corresponding SUBx bit in MODE1 register is equal to ‘0’).

Once sub-addresses have been programmed to their right values, SUBx bits need to be set to ‘1’ in order to have the device acknowledging these addresses (MODE1 register).

Only the 7 MSBs representing the I²C-bus sub-address are valid. The LSB in SUBADRx register is a read-only bit (‘0’).

When SUBx is set to ‘1’, the corresponding I²C-bus sub-address can be used during either an I²C-bus read or write sequence.

7.3.8 LED All Call I²C-bus address, ALLCALLADR

Table 15: ALLCALLADR - LED All Call I²C-bus address register (address 0Ch) bit description

*Legend: * default value*

Address	Register	Bit	Symbol	Access	Value	Description
0Ch	ALLCALLADR	7:1	AC[7:1]	R/W	1110000*	ALLCALL I²C-bus address register
		0	AC[0]	R only	0*	reserved

The LED All Call I²C-bus address allows all the PCA9633s in the bus to be programmed at the same time (ALLCALL bit in register MODE1 must be equal to ‘1’—power-up default state). This address is programmable through the I²C-bus and can be used during either an I²C-bus read or write sequence.

Only the 7 MSBs representing the All Call I²C-bus address are valid. The LSB in ALLCALLADR register is a Read-only bit (‘0’).

If ALLCALL bit = 0, the device does not acknowledge the address programmed in register ALLCALLADR.

7.4 Active LOW output enable input

The active LOW output enable ($\overline{OE}$) pin, allows to enable or disable all the LED outputs at the same time.

This control signal is only available for the 16-pin version and does not apply to the 8-pin or 10-pin versions.

- When a LOW level is applied to $\overline{OE}$ pin, all the LED outputs are enabled and follow the output state defined in the LEDOUT register with the polarity defined by INVRT bit (MODE2 register).
- When a HIGH level is applied to $\overline{OE}$ pin, all the LED outputs are programmed to the value that is defined by OUTNE[1:0] in the MODE2 register.

Table 16: LED outputs when $\overline{OE}$ = 1

OUTNE1	OUTNE0	LED outputs
0	0	0
0	1	1 if OUTDRV = 1, high-impedance if OUTDRV = 0
1	0	high-impedance
1	1	reserved

The $\overline{OE}$ pin can be used as a synchronization signal to switch on/off several PCA9633 devices at the same time. This requires an external clock reference that provides blinking period and the duty cycle.

The $\overline{OE}$ pin can also be used as an external dimming control signal. The frequency of the external clock must be high enough not to be seen by the human eye, and the duty cycle value determines the brightness of the LEDs.

CAUTION

Do not use $\overline{OE}$ as an external blinking control signal when internal global blinking is selected (DMBLNK = 1, MODE2 register) since it will result in an undefined blinking pattern. Do not use $\overline{OE}$ as an external dimming control signal when internal global dimming is selected (DMBLNK = 0, MODE2 register) since it will result in an undefined dimming pattern.

7.5 Power-on reset

When power is applied to V_{DD}, an internal Power-on reset holds the PCA9633 in a reset condition until V_{DD} has reached V_{POR}. At this point, the reset condition is released and the PCA9633 registers and I²C-bus state machine are initialized to their default states—all zeroes—causing all the channels to be deselected. Thereafter, V_{DD} must be lowered below 0.2 V to reset the device.

7.6 Software Reset

The Software Reset Call (SWRST Call) allows all the devices in the I²C-bus to be reset to the power-up state value through a specific formatted I²C-bus command. To be performed correctly, it implies that the I²C-bus is functional and that there is no device hanging the bus.

The SWRST Call function is defined as the following:

1. A START command is sent by the I²C-bus master.
2. The reserved SWRST I²C-bus address '0000011' with the R/$\overline{W}$ bit set to '0' (write) is sent by the I²C-bus master.
3. The PCA9633 device(s) acknowledge(s) after seeing the SWRST Call address '00000110' (0x06) only. If the R/$\overline{W}$ bit is set to '1' (read), no acknowledge is returned to the I²C-bus master.
4. Once the SWRST Call address has been sent and acknowledged, the master sends 2 bytes with 2 specific values (SWRST data byte 1 and byte 2):
   a. Byte 1 = 0xA5: the PCA9633 acknowledges this value only. If byte 1 is not equal to 0xA5, the PCA9633 does not acknowledge it.
   b. Byte 2 = 0x5A: the PCA9633 acknowledges this value only. If byte 2 is not equal to 0x5A, then the PCA9633 does not acknowledge it.

   If more than 2 bytes of data are sent, the PCA9633 does not acknowledge any more.
5. Once the right 2 bytes (SWRST data byte 1 and byte 2 only) have been sent and correctly acknowledged, the master sends a STOP command to end the SWRST Call: the PCA9633 then resets to the default value (power-up value) and is ready to be addressed again within the specified bus free time (t_{BUF}).

The I²C-bus master must interpret a non-acknowledge from the PCA9633 (at any time) as a 'SWRST Call Abort'. The PCA9633 does not initiate a reset of its registers. This happens only when the format of the SWRST Call sequence is not correct.

7.7 Using the PCA9633 with and without external drivers

The PCA9633 LED output drivers are 5.5 V only tolerant and can sink up to 25 mA at 5 V.

If the device needs to drive LEDs to a higher voltage and/or higher current, use of an external driver is required.

- INVRT bit (MODE2 register) can be used to keep the LED PWM control firmware the same (PWMx and GRPPWM values directly calculated from their respective formulas and the LED output state determined by LEDOUT register value) independently of the type of external driver. This bit allows LED output polarity inversion/non-inversion only when $\overline{OE}$ = 0.
- OUTDRV bit (MODE2 register) allows minimizing the amount of external components required to control the external driver (N-type or P-type device).

Table 17: Use of INVRT and OUTDRV based on connection to the LEDn outputs when $\overline{OE}$ = 0 [1]

INVRT	OUTDRV	Direct connection to LEDn		External N-type driver		External P-type driver	
		Firmware	External pull-up resistor	Firmware	External pull-up resistor	Firmware	External pull-up resistor
0	0	formulas and LED output state values apply [2]	LED current limiting R [2]	formulas and LED output state values inverted	required	formulas and LED output state values apply	required
0	1	formulas and LED output state values apply [2]	LED current limiting R [2]	formulas and LED output state values inverted	not required	formulas and LED output state values apply [4]	not required [4]
1	0	formulas and LED output state values inverted	LED current limiting R	formulas and LED output state values apply	required	formulas and LED output state values inverted	required
1	1	formulas and LED output state values inverted	LED current limiting R	formulas and LED output state values apply [3]	not required [3]	formulas and LED output state values inverted	not required

[1] $\overline{OE}$ applies to 16-pin version only. When $\overline{OE}$ = 1, LED output state is controlled only by OUTNE[1:0] bits (MODE2 register).

[2] Correct configuration when LEDs directly connected to the LEDn outputs (connection to V_{DD} through current limiting resistor).

[3] Optimum configuration when external N-type (NPN, NMOS) driver used.

[4] Optimum configuration when external P-type (PNP, PMOS) driver used.

Table 18: Output transistors based on LEDOUT registers, INVRT and OUTDRV bits when $\overline{OE}$ = 0 [1]

LEDOUT	INVRT	OUTDRV	Upper transistor (V_{DD} to LEDn)	Lower transistor (LEDn to V_{SS})	LEDn state
00 LED driver off	0	0	off	off	high-Z [2]
	0	1	on	off	V_{DD}
	1	0	off	on	V_{SS}
	1	1	off	on	V_{SS}
01 LED driver on	0	0	off	on	V_{SS}
	0	1	off	on	V_{SS}
	1	0	off	off	high-Z [2]
	1	1	on	off	V_{DD}
10 Individual brightness control	0	0	off	Individual PWM (non-inverted)	V_{SS}/high-Z [2] = PWMx value
	0	1	Individual PWM (non-inverted)	Individual PWM (non-inverted)	V_{SS}/V_{DD} = PWMx value
	1	0	off	Individual PWM (inverted)	high-Z [2]/V_{SS} = 1 – PWMx value
	1	1	Individual PWM (inverted)	Individual PWM (inverted)	V_{DD}/V_{SS} = 1 – PWMx value
11 Individual + Group dimming/blinking	0	0	off	Individual + Group PWM (non-inverted)	V_{SS}/high-Z [2] = PWMx/GRPPWM values
	0	1	Individual PWM (non-inverted)	Individual PWM (non-inverted)	V_{SS}/V_{DD} = PWMx/GRPPWM values
	1	0	off	Individual + Group PWM (inverted)	high-Z [2]/V_{SS} = (1 – PWMx)/(1 – GRPPWM) values
	1	1	Individual PWM (inverted)	Individual PWM (inverted)	V_{DD}/V_{SS} = (1 – PWMx)/(1 – GRPPWM) values

[1] $\overline{OE}$ applies to 16-pin version only. When $\overline{OE}$ = 1, LED output state is controlled only by OUTNE[1:0] bits (MODE2 register).

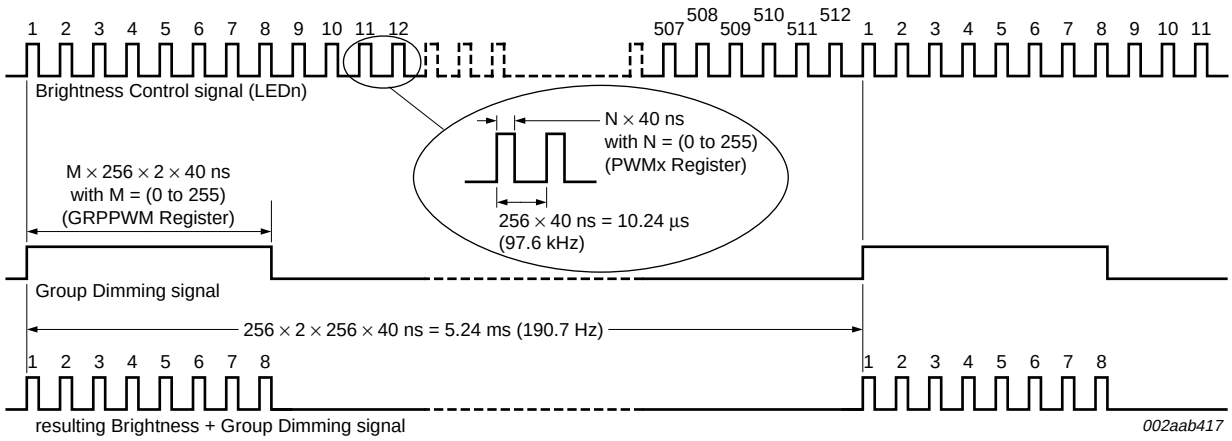
[2] External pull-up or LED current limiting resistor connects LEDn to V_{DD}.

7.8 Individual brightness control with group dimming/blinking

A 97 kHz fixed frequency signal with programmable duty cycle (8 bits, 256 steps) is used to control individually the brightness for each LED.

On top of this signal, one of the following signals can be superimposed (this signal can be applied to the 4 LED outputs):

- A lower 190 Hz fixed frequency signal with programmable duty cycle (8 bits, 256 steps) is used to provide a global brightness control.
- A programmable frequency signal from 24 Hz to $^{1}/_{10.73}$ s (8 bits, 256 steps) with programmable duty cycle (8 bits, 256 steps) is used to provide a global blinking control.



Minimum pulse width for LEDn Brightness Control is 40 ns.

Minimum pulse width for Group Dimming is 20.48 µs.

When M = 1 (GRPPWM register value), the resulting LEDn Brightness Control + Group Dimming signal will have 2 pulses of the LED Brightness Control signal (pulse width = N × 40 ns, with 'N' defined in PWMx register).

This resulting Brightness + Group Dimming signal above shows a resulting Control signal with M = 4 (8 pulses).

Fig 11. Brightness + Group Dimming signals

8. Characteristics of the I²C-bus

The I²C-bus is for 2-way, 2-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

8.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals (see Figure 12).

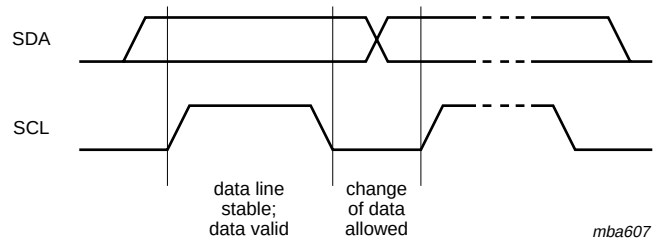


Fig 12. Bit transfer

8.1.1 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition (P) (see Figure 13.)

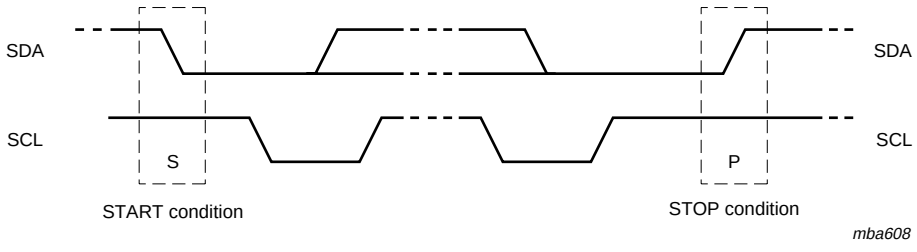


Fig 13. Definition of START and STOP conditions

8.2 System configuration

A device generating a message is a ‘transmitter'; a device receiving is the ‘receiver'. The device that controls the message is the ‘master' and the devices which are controlled by the master are the ‘slaves' (see Figure 14).

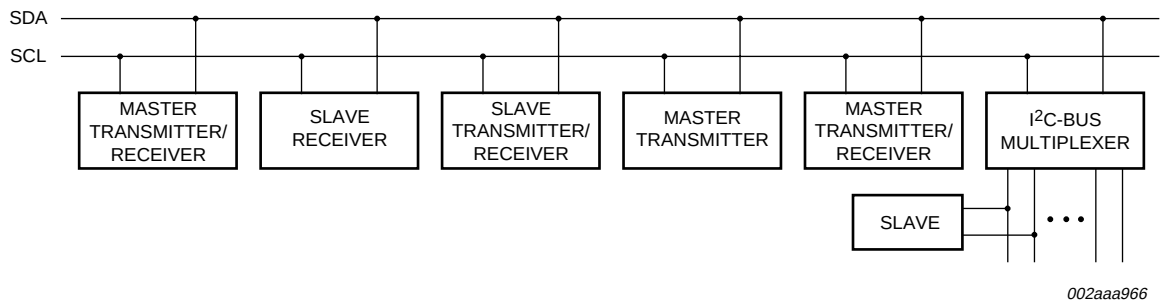


Fig 14. System configuration

8.3 Acknowledge

The number of data bytes transferred between the START and the STOP conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level put on the bus by the transmitter, whereas the master generates an extra acknowledge related clock pulse.

A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse; set-up time and hold time must be taken into account.

A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event, the transmitter must leave the data line HIGH to enable the master to generate a STOP condition.

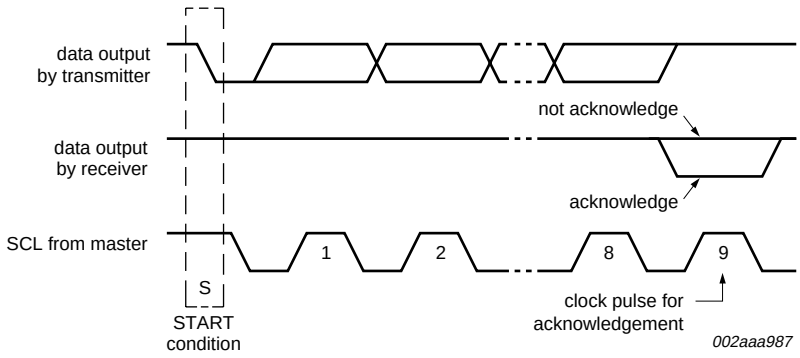
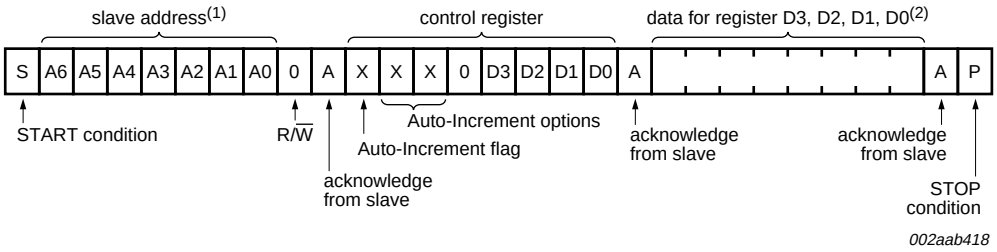


Fig 15. Acknowledgement on the I²C-bus

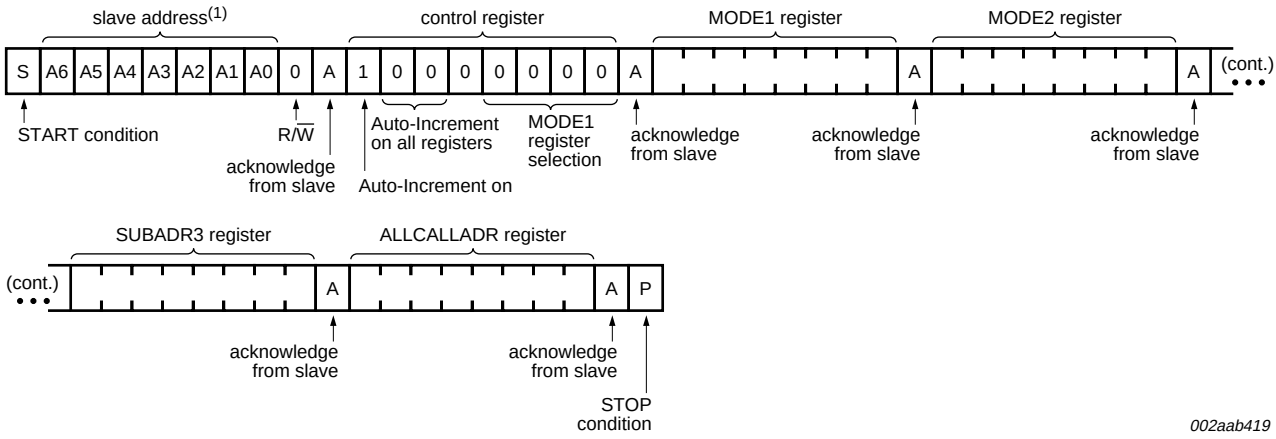
9. Bus transactions



(1) 16-pin version only.

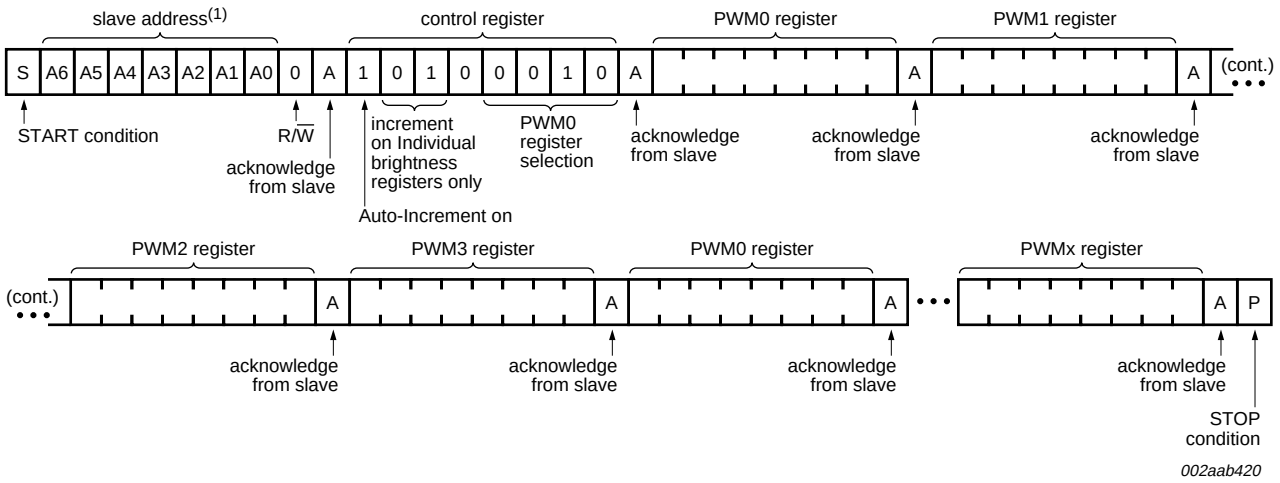
(2) See Table 7 for register definition.

Fig 16. Write to a specific register



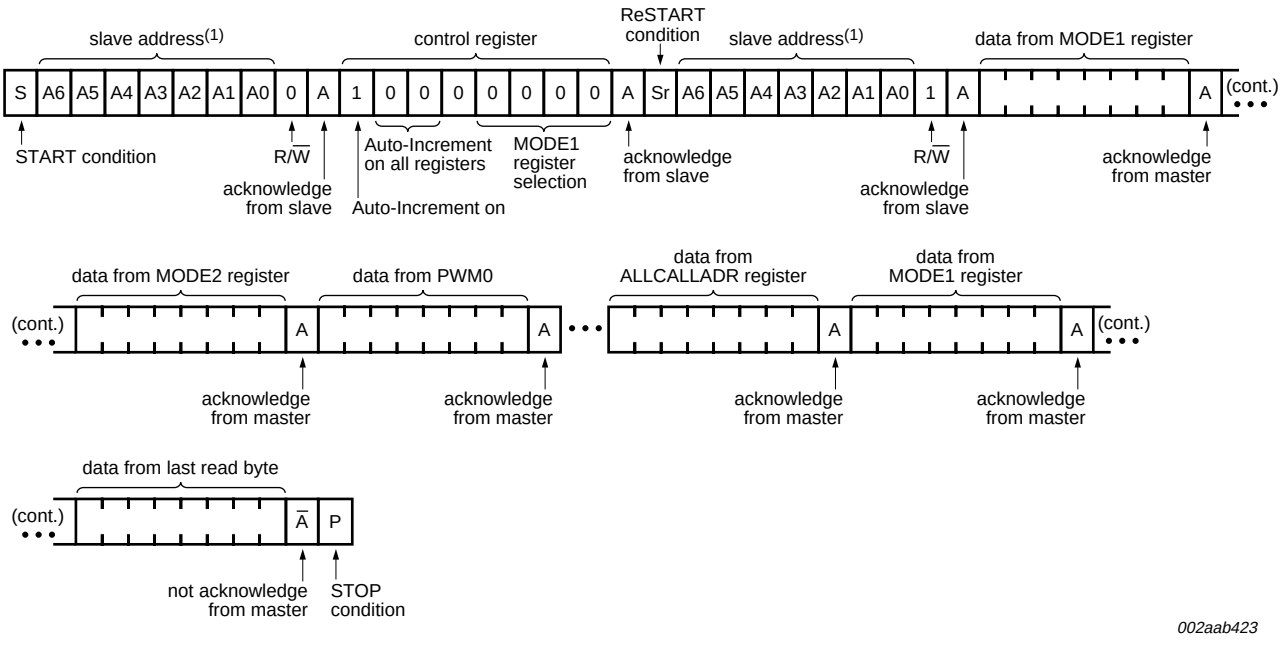
(1) 16-pin version only.

Fig 17. Write to all registers using the Auto-Increment feature



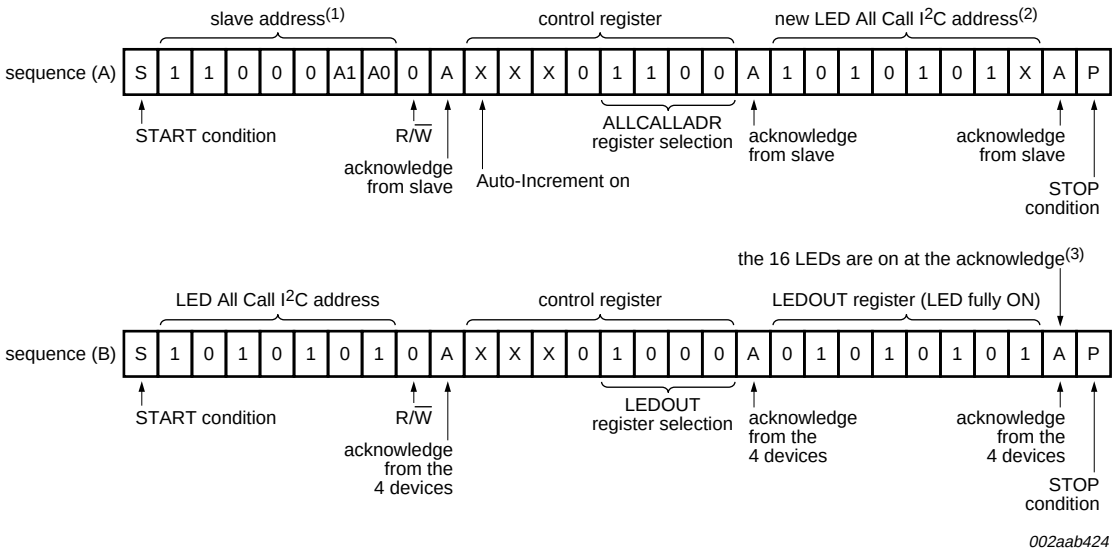
(1) 16-pin version only.

Fig 18. Multiple writes to Individual Brightness registers only using the Auto-Increment feature



(1) 16-pin version only.

Fig 19. Read all registers using the Auto-Increment feature



(1) 10-pin version is used for this figure. Four PCA9633DP2 are used and the same sequence (A) (above) is sent to each of them. A[1:0] = 00 to 11.

(2) ALLCALL bit in MODE1 register is equal to 1 for this example.

(3) OCH bit in MODE2 register is equal to 1 for this example.

Fig 20. LED All Call I²C-bus address programming and LED All Call sequence example

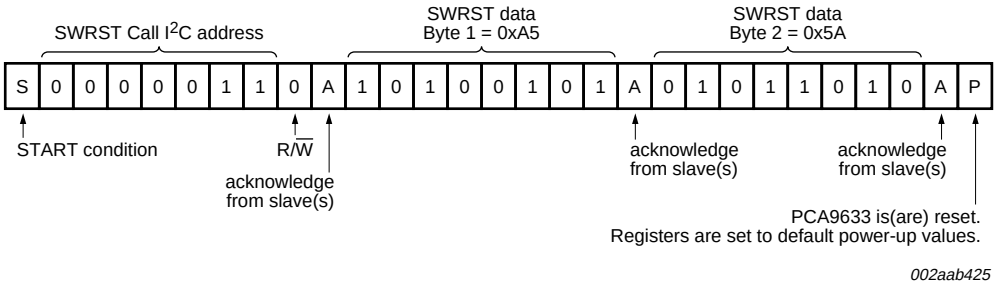
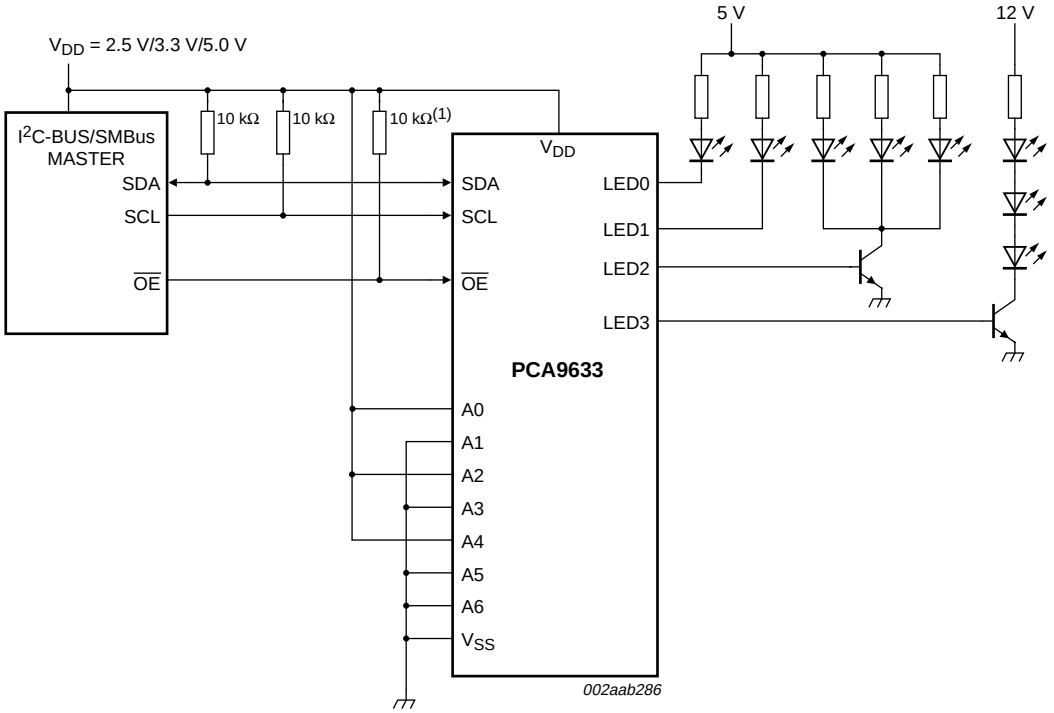


Fig 21. Software Reset (SWRST) Call sequence

10. Application design-in information



(1) $\overline{OE}$ requires pull-up resistor if control signal from the master is open-drain.
I²C-bus address = 0010101

Fig 22. Typical application

11. Limiting values

Table 19: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		–0.5	+6.0	V
$V_{I/O}$	voltage on an input/output pin		V_{SS} – 0.5	5.5	V
$I_{O(LEDn)}$	output current on pin LEDn		-	25	mA
I_{SS}	ground supply current		-	100	mA
P_{tot}	total power dissipation		-	400	mW
T_{stg}	storage temperature		–65	+150	°C
T_{amb}	ambient temperature	operating	–40	+85	°C

12. Static characteristics

Table 20: Static characteristics

V_{DD} = 2.3 V to 5.5 V; V_{SS} = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Supply							
V_{DD}	supply voltage			2.3	-	5.5	V
I_{DD}	supply current	Operating mode; V_{DD} = 2.3 V; no load; f_{SCL} = 1 MHz		-	2.5	10	mA
		Operating mode; V_{DD} = 3.3 V; no load; f_{SCL} = 1 MHz		-	2.5	10	mA
		Operating mode; V_{DD} = 5.5 V; no load; f_{SCL} = 1 MHz		-	2.5	10	mA
I_{stb}	standby current	V_{DD} = 2.3 V; no load; f_{SCL} = 0 Hz; I/O = inputs; $V_I = V_{DD}$		-	2.3	11	µA
		V_{DD} = 3.3 V; no load; f_{SCL} = 0 Hz; I/O = inputs; $V_I = V_{DD}$		-	2.9	12	µA
		V_{DD} = 5.5 V; no load; f_{SCL} = 0 Hz; I/O = inputs; $V_I = V_{DD}$		-	3.8	15.5	µA
V_{POR}	power-on reset voltage	no load; $V_I = V_{DD}$ or V_{SS}	[1]	-	1.70	2.0	V
Input SCL; input/output SDA							
V_{IL}	LOW-level input voltage			−0.5	-	+0.3V_{DD}	V
V_{IH}	HIGH-level input voltage			0.7V_{DD}	-	5.5	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; V_{DD} = 2.3 V		20	-	-	mA
		V_{OL} = 0.4 V; V_{DD} = 5.0 V		30	-	-	mA
I_L	leakage current	$V_I = V_{DD}$ or V_{SS}		−1	-	+1	µA
C_i	input capacitance	$V_I = V_{SS}$		-	6	10	pF
LED driver outputs							
I_{OL}	LOW-level output current	V_{OL} = 0.5 V; V_{DD} = 2.3 V		12	-	-	mA
		V_{OL} = 0.5 V; V_{DD} = 3.0 V		17	-	-	mA
		V_{OL} = 0.5 V; V_{DD} = 4.5 V		25	-	-	mA
$I_{OL(tot)}$	total LOW-level output current	V_{OL} = 0.5 V; V_{DD} = 4.5 V		-	-	100	mA
I_{OH}	HIGH-level output current	open-drain; $V_{OH} = V_{DD}$		−50	-	+50	µA
V_{OH}	HIGH-level output voltage	I_{OH} = −10 mA; V_{DD} = 2.3 V		1.6	-	-	V
		I_{OH} = −10 mA; V_{DD} = 3.0 V		2.3	-	-	V
		I_{OH} = −10 mA; V_{DD} = 4.5 V		4.0	-	-	V
C_o	output capacitance			-	2.5	5	pF
$\overline{OE}$ input							
V_{IL}	LOW-level input voltage			−0.5	-	+0.8	V
V_{IH}	HIGH-level input voltage			2	-	5.5	V
I_{LI}	input leakage current			−1	-	+1	µA
C_i	input capacitance			-	3.7	5	pF

Table 20: Static characteristics *...continued*

V_{DD} = 2.3 V to 5.5 V; V_{SS} = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Address inputs						
V_{IL}	LOW-level input voltage		−0.5	-	$+0.3V_{DD}$	V
V_{IH}	HIGH-level input voltage		$0.7V_{DD}$	-	5.5	V
I_{LI}	input leakage current		−1	-	+1	µA
C_i	input capacitance		-	3.7	5	pF

[1] V_{DD} must be lowered to 0.2 V in order to reset part.

13. Dynamic characteristics

Table 21: Dynamic characteristics

Symbol	Parameter	Conditions	Standard mode I²C-bus		Fast mode I²C-bus		Fast+ mode I²C-bus		Unit
			Min	Max	Min	Max	Min	Max	
f_{SCL}	SCL clock frequency	[1]	0	100	0	400	0	1000	kHz
t_{BUF}	bus free time between a STOP and START condition		4.7	-	1.3	-	0.5	-	µs
$t_{HD;STA}$	hold time (repeated) START condition		4.0	-	0.6	-	0.26	-	µs
$t_{SU;STA}$	set-up time for a repeated START condition		4.7	-	0.6	-	0.26	-	µs
$t_{SU;STO}$	set-up time for STOP condition		4.0	-	0.6	-	0.26	-	µs
$t_{HD;DAT}$	data hold time		0	-	0	-	0	-	ns
$t_{VD;ACK}$	data valid acknowledge time	[2]	0.3	3.45	0.1	0.9	0.05	0.45	µs
$t_{VD;DAT}$	data valid time	[3]	0.3	3.45	0.1	0.9	0.05	0.45	µs
$t_{SU;DAT}$	data set-up time		250	-	100	-	50	-	ns
t_{LOW}	LOW period of the SCL clock		4.7	-	1.3	-	0.5	-	µs
t_{HIGH}	HIGH period of the SCL clock		4.0	-	0.6	-	0.26	-	µs
t_f	fall time of both SDA and SCL signals	[5] [6]	-	300	$20 + 0.1 C_b$ [4]	300	-	120	ns
t_r	rise time of both SDA and SCL signals		-	1000	$20 + 0.1 C_b$ [4]	300	-	120	ns
t_{SP}	pulse width of spikes that must be suppressed by the input filter	[7]	-	50	-	50	-	50	ns

[1] Minimum SCL clock frequency is limited by the bus time-out feature, which resets the serial bus interface if either SDA or SCL is held LOW for a minimum of 25 ms. Disable bus time-out feature for DC operation.

[2] $t_{VD;ACK}$ = time for Acknowledgement signal from SCL LOW to SDA (out) LOW.

[3] $t_{VD;DAT}$ = minimum time for SDA data out to be valid following SCL LOW.

[4] C_b = total capacitance of one bus line in pF.

[5] A master device must internally provide a hold time of at least 300 ns for the SDA signal (refer to the V_{IL} of the SCL signal) in order to bridge the undefined region of SCL's falling edge.

[6] The maximum t_f for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time (t_f) for the SDA output stage is specified at 250 ns. This allows series protection resistors to be connected between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified t_f.

[7] Input filters on the SDA and SCL inputs suppress noise spikes less than 50 ns.

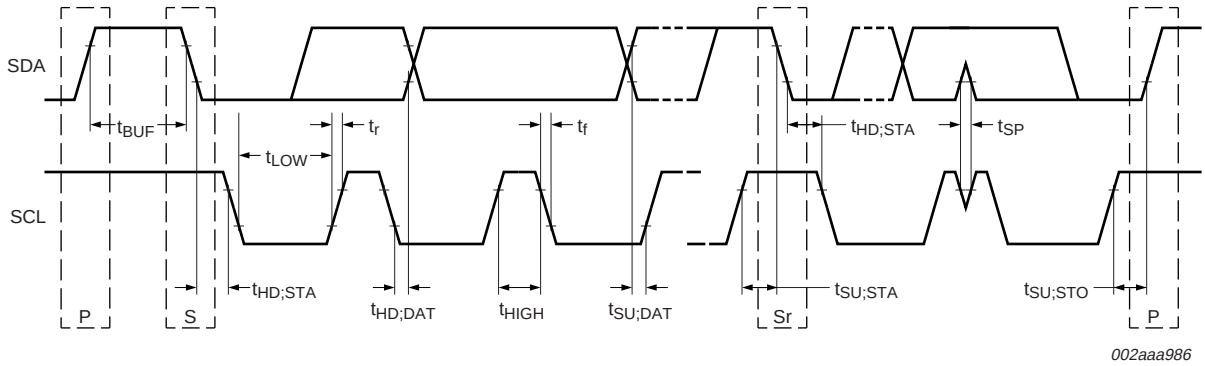
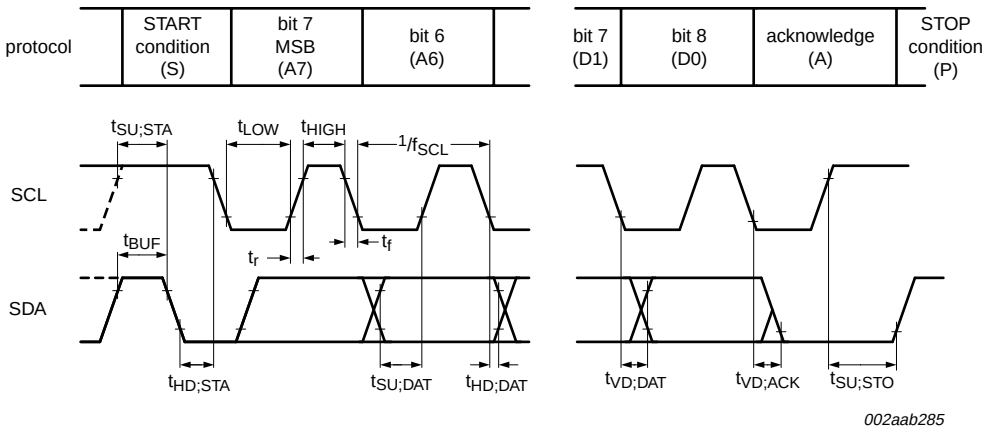


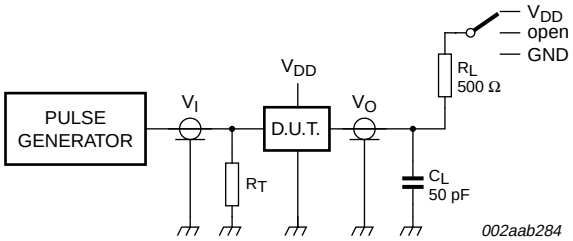
Fig 23. Definition of timing



Rise and fall times refer to V_{IL} and V_{IH}.

Fig 24. I²C-bus timing diagram

14. Test information



R_L = Load resistor for LEDn. R_L for SDA and SCL > 1 kΩ (3 mA or less current).

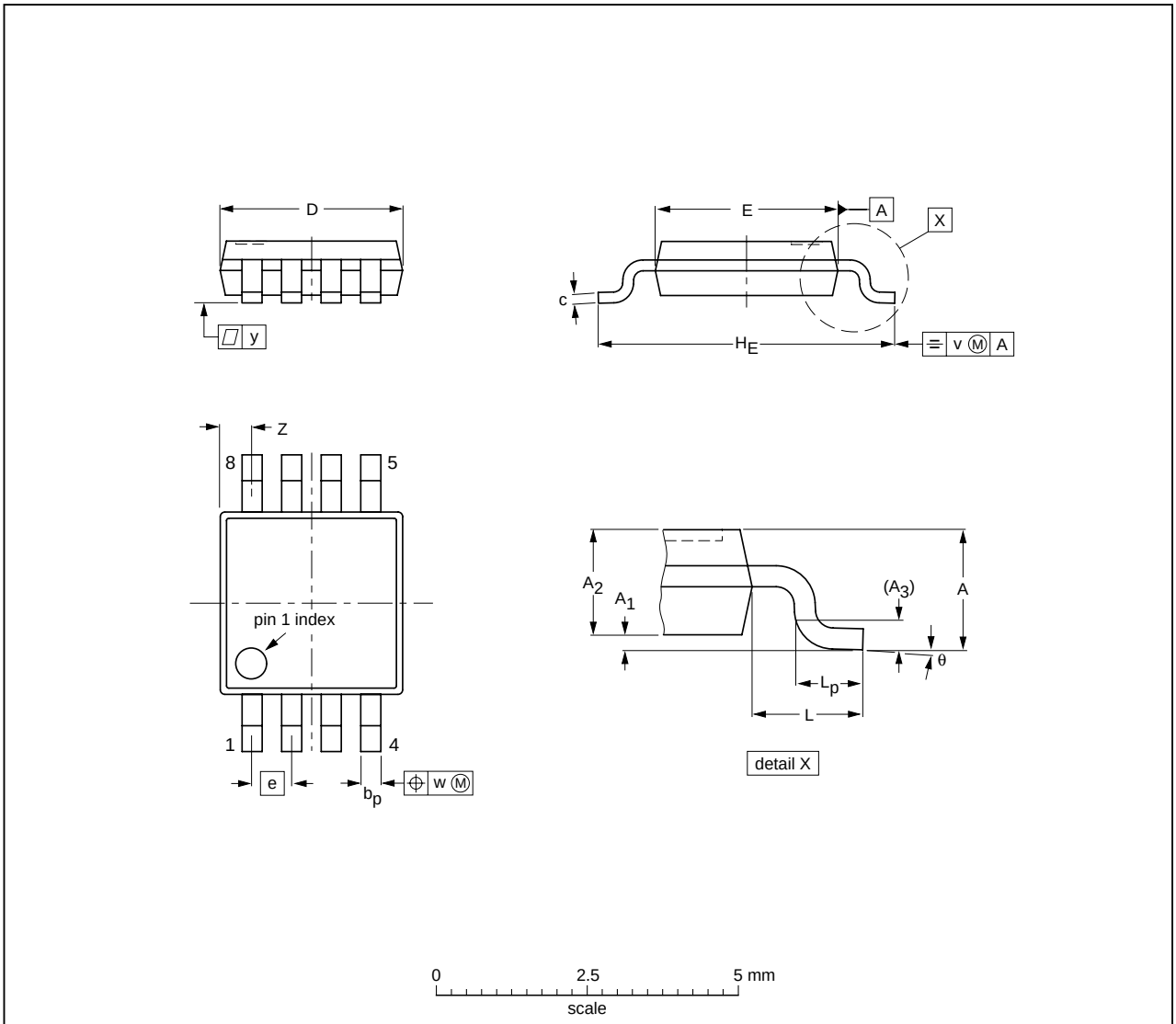
C_L = Load capacitance includes jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generators.

Fig 25. Test circuitry for switching times

15. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm **SOT505-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	v	w	y	$Z^{(1)}$	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.45 0.25	0.28 0.15	3.1 2.9	3.1 2.9	0.65	5.1 4.7	0.94	0.7 0.4	0.1	0.1	0.1	0.70 0.35	6° 0°

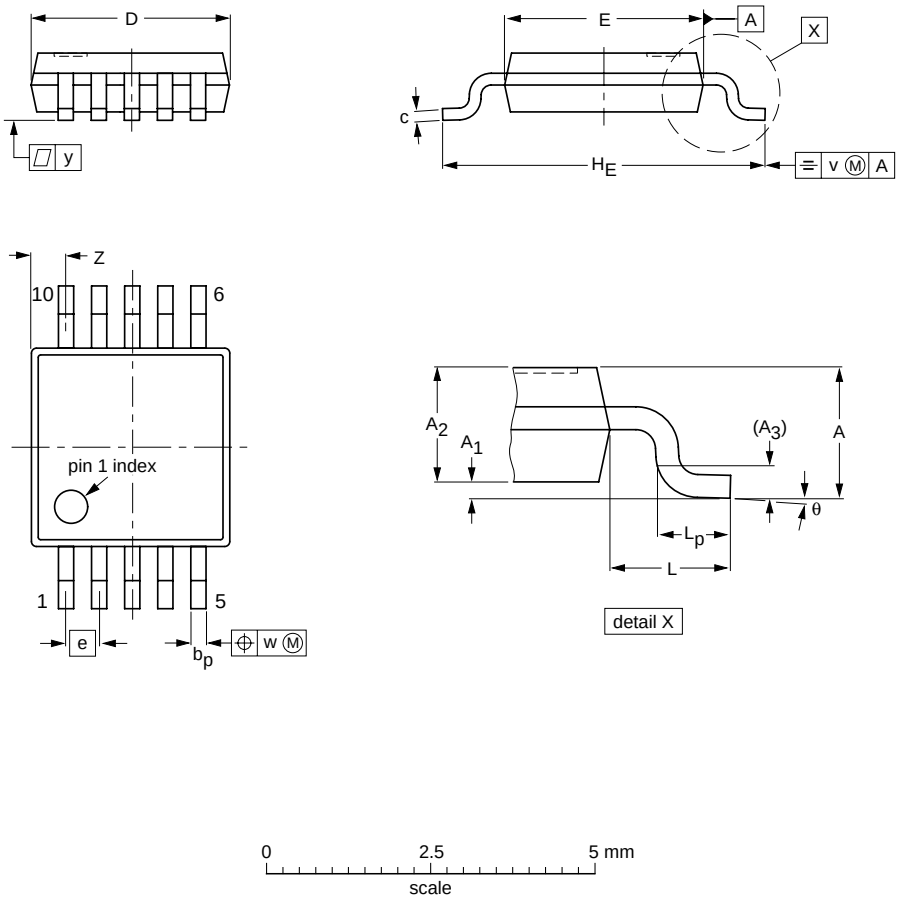
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT505-1						~~99-04-09~~ 03-02-18

Fig 26. Package outline SOT505-1 (TSSOP8)

TSSOP10: plastic thin shrink small outline package; 10 leads; body width 3 mm **SOT552-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	v	w	y	$Z^{(1)}$	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.15	0.23 0.15	3.1 2.9	3.1 2.9	0.5	5.0 4.8	0.95	0.7 0.4	0.1	0.1	0.1	0.67 0.34	6° 0°

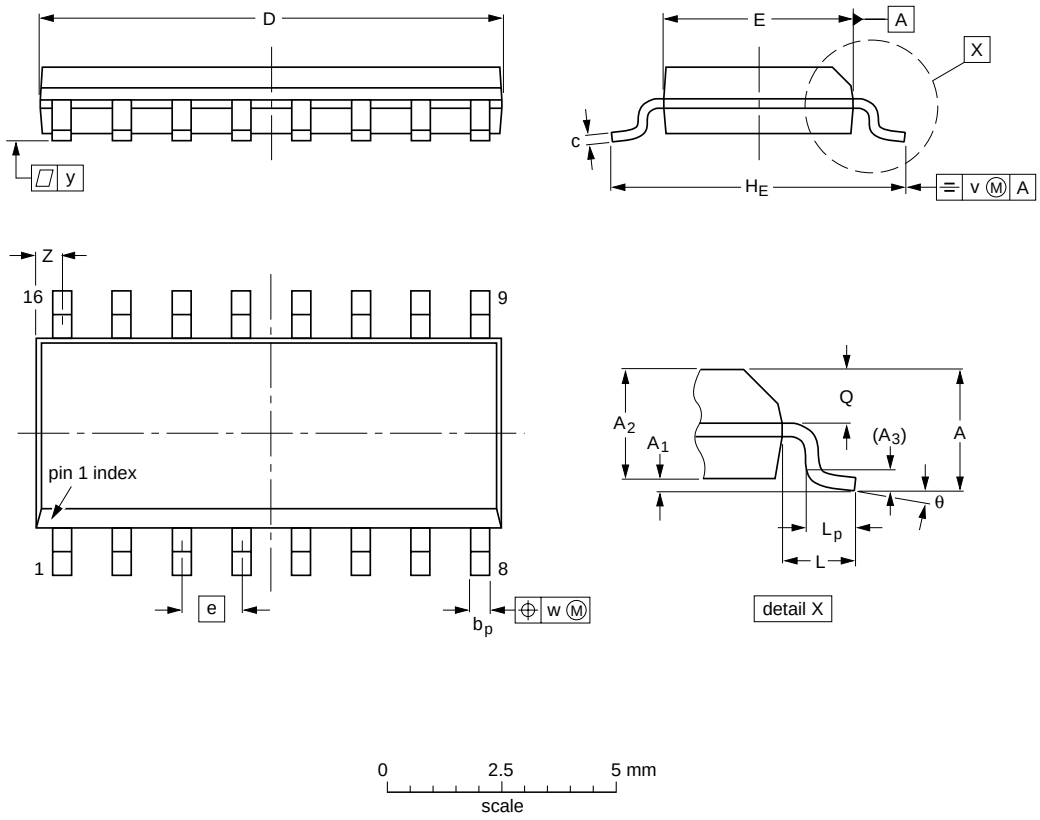
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT552-1						~~99-07-29~~ 03-02-18

Fig 27. Package outline SOT552-1 (TSSOP10)

SO16: plastic small outline package; 16 leads; body width 3.9 mm **SOT109-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D(1)	E(1)	e	H_E	L	L_p	Q	v	w	y	Z(1)	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

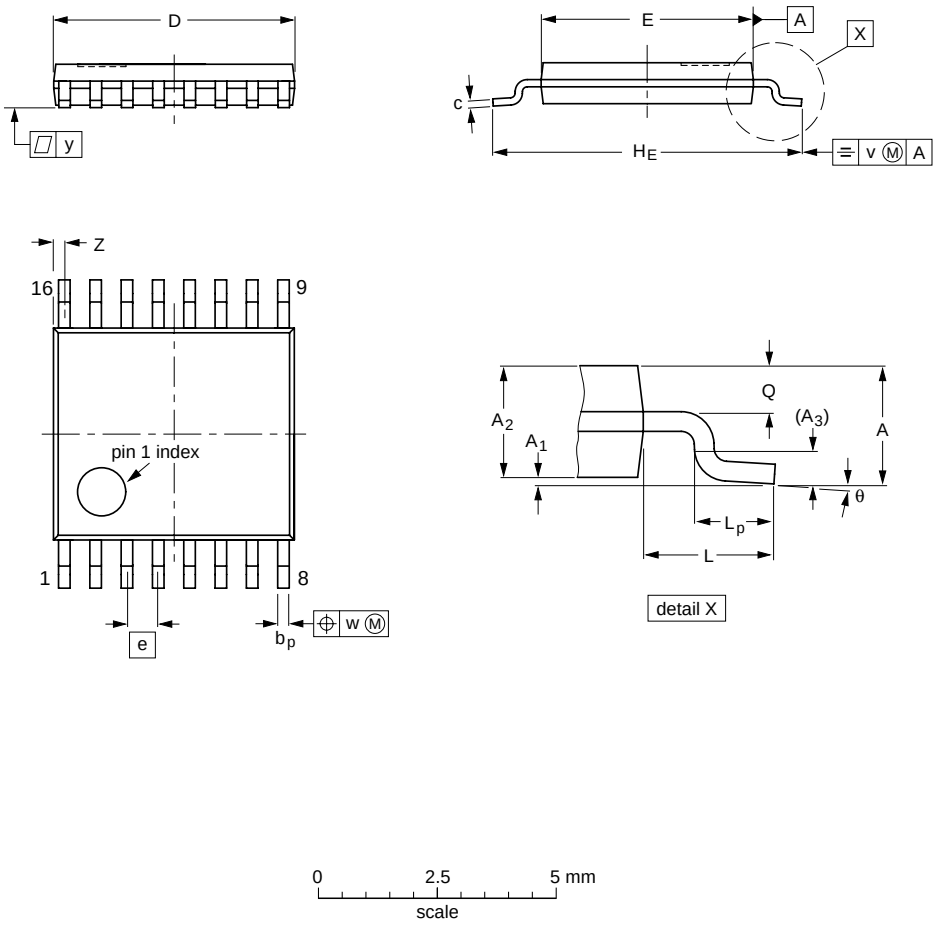
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				~~99-12-27~~ 03-02-19

Fig 28. Package outline SOT109-1 (SO16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8^o 0^o

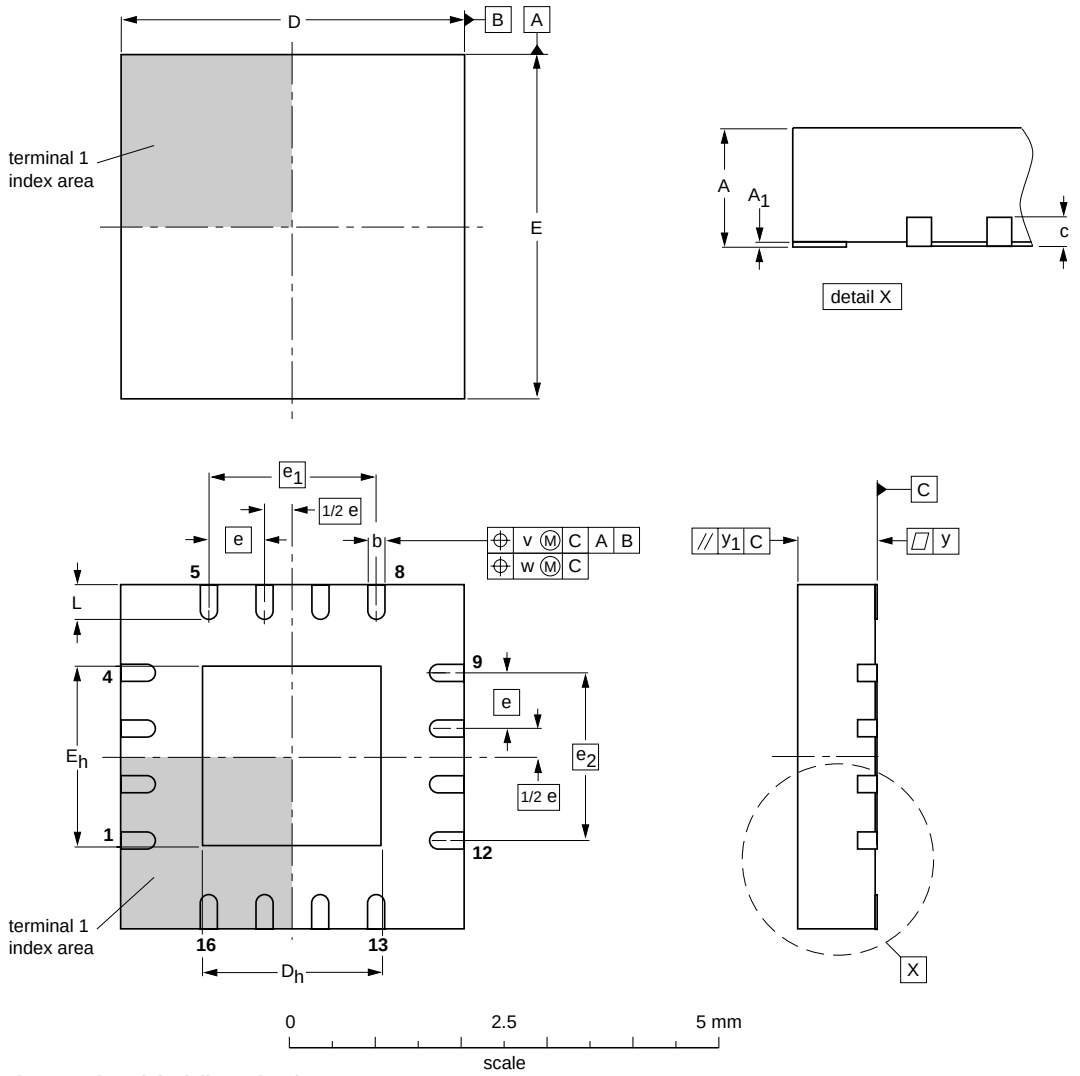
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig 29. Package outline SOT403-1 (TSSOP16)

HVQFN16: plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 4 x 4 x 0.85 mm **SOT629-1**



DIMENSIONS (mm are the original dimensions)

UNIT	$A^{(1)}$ max.	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	1	0.05 0.00	0.38 0.23	0.2	4.1 3.9	2.25 1.95	4.1 3.9	2.25 1.95	0.65	1.95	1.95	0.75 0.50	0.1	0.05	0.05	0.1

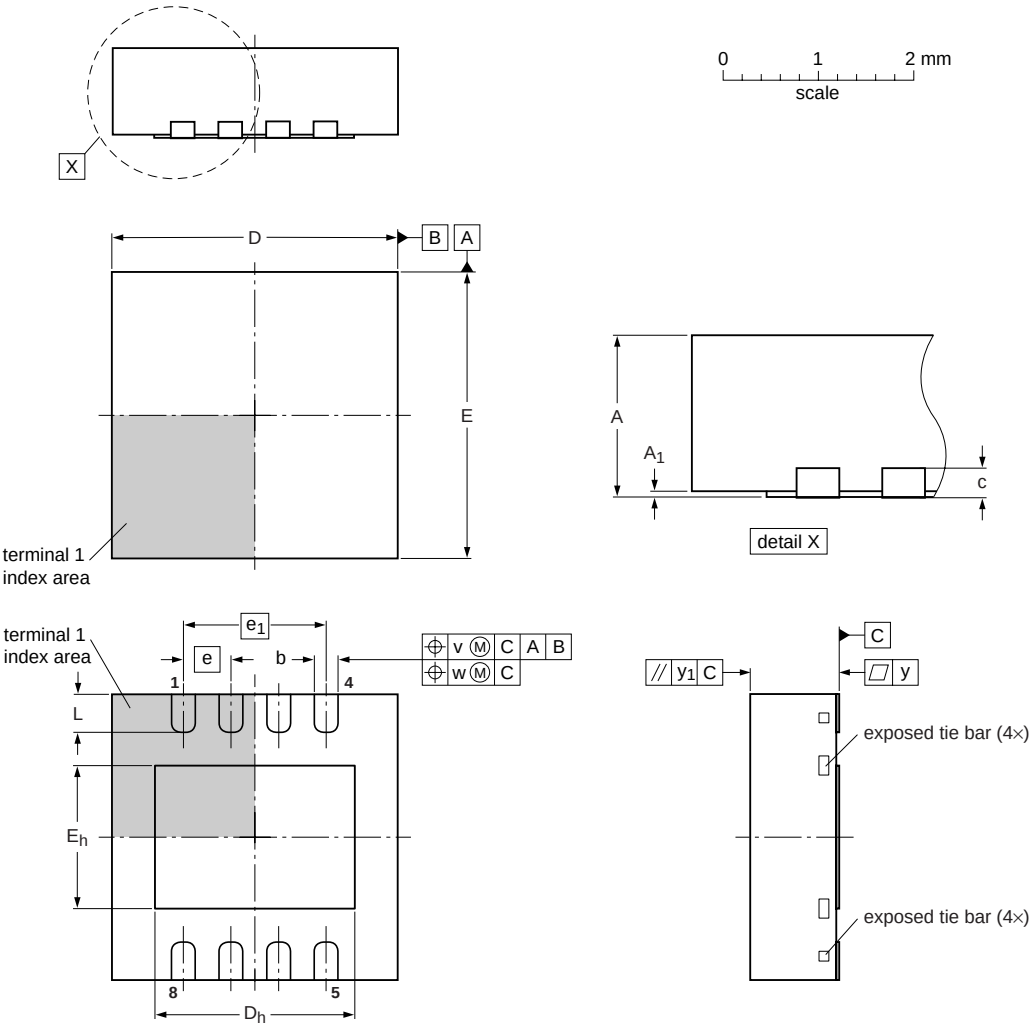
Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT629-1	- - -	MO-220	- - -			~~01-08-08~~ 02-10-22

Fig 30. Package outline SOT629-1 (HVQFN16)

HVSON8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3 x 3 x 0.85 mm **SOT908-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	A_1	b	c	D(1)	D_h	E(1)	E_h	e	e_1	L	v	w	y	y_1
mm	1	0.05 0.00	0.3 0.2	0.2	3.1 2.9	2.25 1.95	3.1 2.9	1.65 1.35	0.5	1.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT908-1		MO-229				~~05-09-26~~ 05-10-05

Fig 31. Package outline SOT908-1 (HVSON8)

16. Handling information

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be completely safe you must take normal precautions appropriate to handling integrated circuits.

17. Soldering

17.1 Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *Data Handbook IC26; Integrated Circuit Packages* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

17.2 Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 seconds and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 °C to 270 °C depending on solder paste material. The top-surface temperature of the packages should preferably be kept:

- below 225 °C (SnPb process) or below 245 °C (Pb-free process)
  - for all BGA, HTSSON..T and SSOP..T packages
  - for packages with a thickness ≥ 2.5 mm
  - for packages with a thickness < 2.5 mm and a volume ≥ 350 mm^3 so called thick/large packages.
- below 240 °C (SnPb process) or below 260 °C (Pb-free process) for packages with a thickness < 2.5 mm and a volume < 350 mm^3 so called small/thin packages.

Moisture sensitivity precautions, as indicated on packing, must be respected at all times.

17.3 Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

  The footprint must incorporate solder thieves at the downstream end.
- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time of the leads in the wave ranges from 3 seconds to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

17.4 Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 seconds to 5 seconds between 270 °C and 320 °C.

17.5 Package related soldering information

Table 22: Suitability of surface mount IC packages for wave and reflow soldering methods

Package [1]	Soldering method	
	Wave	Reflow [2]
BGA, HTSSON..T [3], LBGA, LFBGA, SQFP, SSOP..T [3], TFBGA, VFBGA, XSON	not suitable	suitable
DHVQFN, HBCC, HBGA, HLQFP, HSO, HSOP, HSQFP, HSSON, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable [4]	suitable
PLCC [5], SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended [5] [6]	suitable
SSOP, TSSOP, VSO, VSSOP	not recommended [7]	suitable
CWQCCN..L [8], PMFP [9], WQCCN..L [8]	not suitable	not suitable

[1] For more detailed information on the BGA packages refer to the *(LF)BGA Application Note* (AN01026); order a copy from your Philips Semiconductors sales office.

[2] All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods*.

[3] These transparent plastic packages are extremely sensitive to reflow soldering conditions and must on no account be processed through more than one soldering cycle or subjected to infrared reflow soldering with peak temperature exceeding 217 °C ± 10 °C measured in the atmosphere of the reflow oven. The package body peak temperature must be kept as low as possible.

[4] These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.

[5] If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.

[6] Wave soldering is suitable for LQFP, QFP and TQFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.

[7] Wave soldering is suitable for SSOP, TSSOP, VSO and VSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

[8] Image sensor packages in principle should not be soldered. They are mounted in sockets or delivered pre-mounted on flex foil. However, the image sensor package can be mounted by the client on a flex foil by using a hot bar soldering process. The appropriate soldering profile can be provided on request.

[9] Hot bar soldering or manual soldering is suitable for PMFP packages.

18. Abbreviations

Table 23: Abbreviations

Acronym	Description
CDM	Charged Device Model
ESD	ElectroStatic Discharge
HBM	Human Body Model
I²C-bus	Inter IC bus
LED	Light Emitting Diode
LSB	Least Significant Bit
MM	Machine Model
PCB	Printed-Circuit Board
PWM	Pulse Width Modulation
RGB	Red/Green/Blue
RGBA	Red/Green/Blue/Amber
SMBus	System Management Bus

19. Revision history

Table 24: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
PCA9633_1	20060123	Product data sheet	-	9397 750 14614	-

20. Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

21. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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25. Contents

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